

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJ4153
Package Type :	SOT-523

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.1596%
Lead Frame-A	Copper	7440-50-8	2.00%	49.4894%
	Iron	7439-89-6	55.00%	
	Nickel	7440-02-0	41.40%	
	Manganese	7439-96-5	0.80%	
	Silicon	7440-21-3	0.30%	
	Carbon	7440-44-0	0.05%	
	Aluminum	7429-90-5	0.10%	
	Chromium	7440-47-3	0.10%	
	Cobalt	7440-48-4	0.20%	
	Phosphorus	7723-14-0	0.03%	
	Sulphur	7704-34-9	0.03%	
Lead Frame-B (Optional)	Copper	7440-50-8	97.459%	0.1904%
	Iron	7439-89-6	2.30%	
	Phosphorus	7723-14-0	0.10%	
	Zinc	7440-66-6	0.10%	
	Lead	7439-92-1	0.001%	
	Silver	7440-22-4	0.04%	
Wire	Copper	7440-50-8	99.99%	44.4845%
	Others	/	0.001%	
Mold Compound	Silica	60676-86-0	87.50%	4.6761%
	Epoxy Resin	29690-82-2	6.00%	
	Phenol Resin	Trade secret	6.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.99%	0.01%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.